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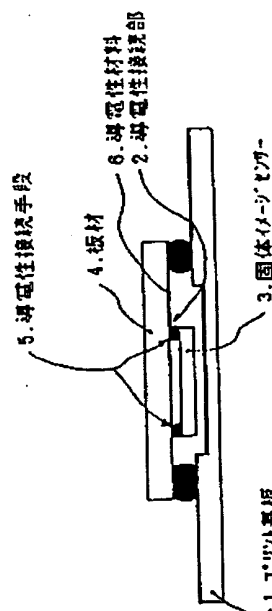
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TITLE : SOLID-STATE IMAGE SENSOR



ABSTRACT : PURPOSE: To reduce a drop in a yield due to dust particles or the like which are mixed and to sharply reduce a cost by a method wherein a conductive connection part of a solid-state image sensor and a patterned conductive connection part of a sheet material are connected directly by a conductive connection means such as a conductive adhesive, gold, a solder or the like.

CONSTITUTION: A conductive material 6 is patterned on a sheet material 4 composed of a transparent material such as a plastic sheet, a glass sheet or the like; a conductive connection part 2 and a conductive connection part of a solid-state image sensor 3 are connected directly by a conductive connection means 5 such as a conductive adhesive, gold, a solder or the like. The solid-state image sensor which has been sealed in this manner may be connected, as required, to a substrate into which other electronic circuits have been assembled, such as a printed-circuit board 1, by a soldering operation by using the conductive adhesive; it may be assembled into another package by a means such as the soldering operation or the like.

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